



PATENT ABSTRACTS OF JAPAN

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(71) Applicant: FUJITSU LTD

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(74) Representative:

(54) SURFACE MOUNTING
STRUCTURE USING BUMP
ELECTRODE AND
MIDDLE SUBSTRATE

(57) Abstract:

PROBLEM TO BE SOLVED: To improve the reliability of mounting structure by preventing separation from occurring in bump electrodes.

SOLUTION: In the surface mounting structure using bump electrodes, where a ceramic circuit board 11 is mounted in the surface of a printed wiring board 12 different is thermal expansion coefficient from the ceramic circuit board, using first and second solder bumps 14 and 15, a middle board 13 which has a thermal expansion adsorbing mechanism to relax the thermal expansion of each circuit board 11 and 12 is interposed between the ceramic circuit board 11 and the printed wiring board 12.

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